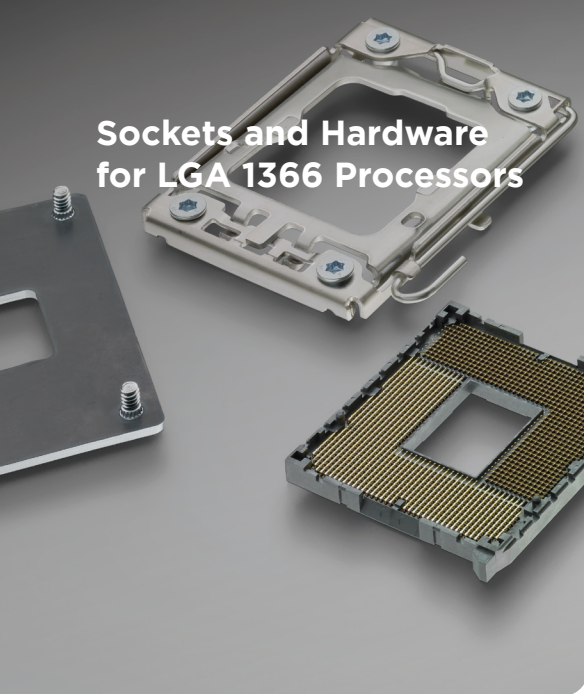


Introducing Sockets and Hardware for LGA 1366 Processors

TE Connectivity's surface mount LGA socket was designed for use with Intel's® Core™ i7 LGA 1366 processor. The contacts have .64mm diameter solder balls for surface mount onto the PCB, while the top side provides a cantilever beam interface to the package. The integrated lever mechanism (ILM) generates the Z-axis compression load. A robust bolster plate helps eliminate PCB bowing during compression. The sockets are validated to Intel Design Guides.



Sockets and Hardware for LGA 1366 Processors



KEY FEATURES

- 1366 contacts with a 1.016mm x 1.016mm grid.
- Available with 15 or 30 Gold contact plating.
- Socket housing facilitates efficient soldering to the PCB board.
- Socket is supplied with a cap to facilitate vacuum pick and place. Spare caps can be ordered separately.
- Two backplate options for use in desktop or server applications.
- ILM and backplate must be ordered separately. Kits are also available for ease in ordering.

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APPLICATIONS

- Servers
- High End desktop computers

ELECTRICAL

- Low level bulk contact resistance: 15 milliohms max avg.
- Insulation resistance: 800 milliohms min. @ 500 VDC

MECHANICAL

- Nominal Deflection: .5 mm
- Durability: 30 cycles
- Mating and Unmating force of Lever: 49N max

MATERIALS

- Socket assembly
Contact: Copper Alloy, gold plating on contact area over nickel plating.
Base housing: Thermoplastic UL94V-0
Cap: Thermoplastic UL94V-0
- ILM load plate and lever: Stainless steel
- ILM frame, nut and collar: Steel
- Backplate assembly: Steel
- Insulator: Polypropylene

APPLICATIONS AND SPECIFICATION

- Application specification 114-5432
- Product specification 108-78496

PRODUCT OFFERINGS

Part Number	Description	Plating	Solder Ball
1981837-1	LGA 1366 Socket	15 Gold	Lead Free
1981837-2	LGA 1366 Socket	30 Gold	Lead Free
1-1981837-2	LGA 1366 Socket	30 Gold	Leaded
1939738-1	ILM U Lever		
1-1939738-2	ILM Straight Lever		
1-1939738-1	Short Straight Lever		
1939739-1	Desktop Back Plate		
1981467-1	Server Back Plate		
1-1981374-1	Spare socket cap		

ILM/Back Plate Kits

Part No.	1939738-1 U Lever	1-1939738-2 Straight Lever	1-1939738-1 Short Straight Lever	1939739-1 Desktop Back Plate	1981467-1 Server Back Plate
2040865-1	1			1	
2040865-2	1				1
2040865-3		1		1	
2040865-4		1			1
2040865-9			1	1	
1-2040865-0			1		1



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